

UG554: xG27 Dev Kit User's Guide

The xG27 Dev Kit is a low-cost, small form factor prototype and development platform for the EFR32BG27 Wireless Gecko System-on-Chip.

The board is a small and cost-effective, feature-rich, prototype and development platform based on the EFR32™ Wireless Gecko System-on-Chip. The xG27 Dev Kit is an ideal platform for developing energy-friendly connected IoT devices.

The xG27 Dev Kit ships with a Bluetooth demo that works with a cloud connected smart-phone app, showcasing easy collection of environmental and motion sensor data, as well as button and LED control.

A built in SEGGER J-Link debugger ensures easy debugging through the USB Micro-B connector.



TARGET DEVICE

- EFR32 Wireless Gecko System-on-Chip (EFR32BG27C140F768IM40)
 - Cortex-M33 w/FPU with 76.8 MHz maximum operating frequency
 - 512 kB flash and 32 kB RAM
 - Energy-efficient radio core with low active and sleep currents
 - Bluetooth 5.2 Direction Finding
 - Integrated PA with up to 8 dBm (2.4 GHz) TX power
 - Secure Boot with Root of Trust and Secure Loader (RTSL)

KIT FEATURES

- 2.4 GHz ceramic chip antenna
- Power control of on-board peripherals for ultra-low-power operation
- Relative humidity and temperature sensor
- Ambient light sensor
- Hall effect sensor
- 6-axis inertial sensor
- PDM stereo microphones
- 8 Mbit flash for OTA programming and data logging
- User LED and push button
- 20-pin 2.54 mm breakout pads
- SEGGER J-Link on-board debugger
- Virtual COM port
- Packet Trace Interface (PTI)
- Mini Simplicity connector for AEM and packet trace using external Silicon Labs debugger
- USB or coin cell battery powered.

SOFTWARE SUPPORT

- Simplicity Studio™

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1. Introduction

The xG27 Dev Kit (OPN: xG27-DK2602A) has been designed to inspire customers to make battery-operated IoT devices with the Silicon Labs EFR32BG27 Wireless Gecko System-on-Chip. The highlights of the board include four different environmental sensors and stereo PDM microphones accessible to the EFR32BG27 wireless MCU. The peripherals have been grouped into power domains that can be turned on and off by the application code as needed.

Programming the xG27 Dev Kit is easily done using a USB Micro-B cable and the on-board J-Link debugger. A USB virtual COM port provides a serial connection to the target application, and the Packet Trace Interface (PTI) offers invaluable debug information about transmitted and received packets in wireless links. Included on the board is an 8 Mbit serial flash that can be used for Over-The-Air (OTA) firmware upgrade, or as a general purpose non-volatile memory. The xG27 Dev Kit is supported in Simplicity Studio™, and a Board Support Package (BSP) is provided to give application developers a flying start.

Energy profiling and advanced wireless network analysis and debugging tools are available through the provided Mini Simplicity Connector using an external Silicon Labs debugger.

Connecting external hardware to the xG27 Dev Kit can be done using the 20 breakout pads, which present peripherals from the EFR32BG27 Wireless Gecko such as I²C, SPI, UART, and GPIOs. The breakout pads follow the same pinout as the expansion headers (EXP) on other Silicon Labs Starter Kits.

1.1 Kit Contents

The following items are included in the box:

- 1x xG27 Dev Kit board (BRD2602A).

1.2 Getting Started

Detailed instructions for how to get started with your new xG27 Dev Kit can be found on the Silicon Labs web page: <https://www.silabs.com/dev-tools>

1.3 Hardware Content

The following key hardware elements are included on the xG27 Dev Kit:

- EFR32BG27 Wireless Gecko SoC with 76.8 MHz operating frequency, 512 kB flash, and 32 kB RAM
- 2.4 GHz ceramic antenna for wireless transmission
- Silicon Labs Si7021 relative humidity and temperature sensor
- Silicon Labs Si7210 hall effect sensor
- Vishay VEML6035 ambient light sensor
- TDK InvenSense ICM-20689 6-axis inertial sensor
- Two Knowles SPK0641HT4H-1 MEMS microphones
- Macronix ultra low power 8 Mbit SPI flash (MX25R8035F)
- One LED and one push button
- Power enable signals and isolation switches for ultra-low power operation
- On-board SEGGER J-Link debugger for easy programming and debugging, which includes a USB virtual COM port and Packet Trace Interface (PTI)
- Mini Simplicity connector for access to energy profiling and advanced wireless network debugging
- Breakout pads for GPIO access and connection to external hardware
- Reset button
- Automatic switchover between USB and battery power
- CR2032 coin cell holder

1.4 Kit Hardware Layout

xG27 Dev Kit layout is shown below.

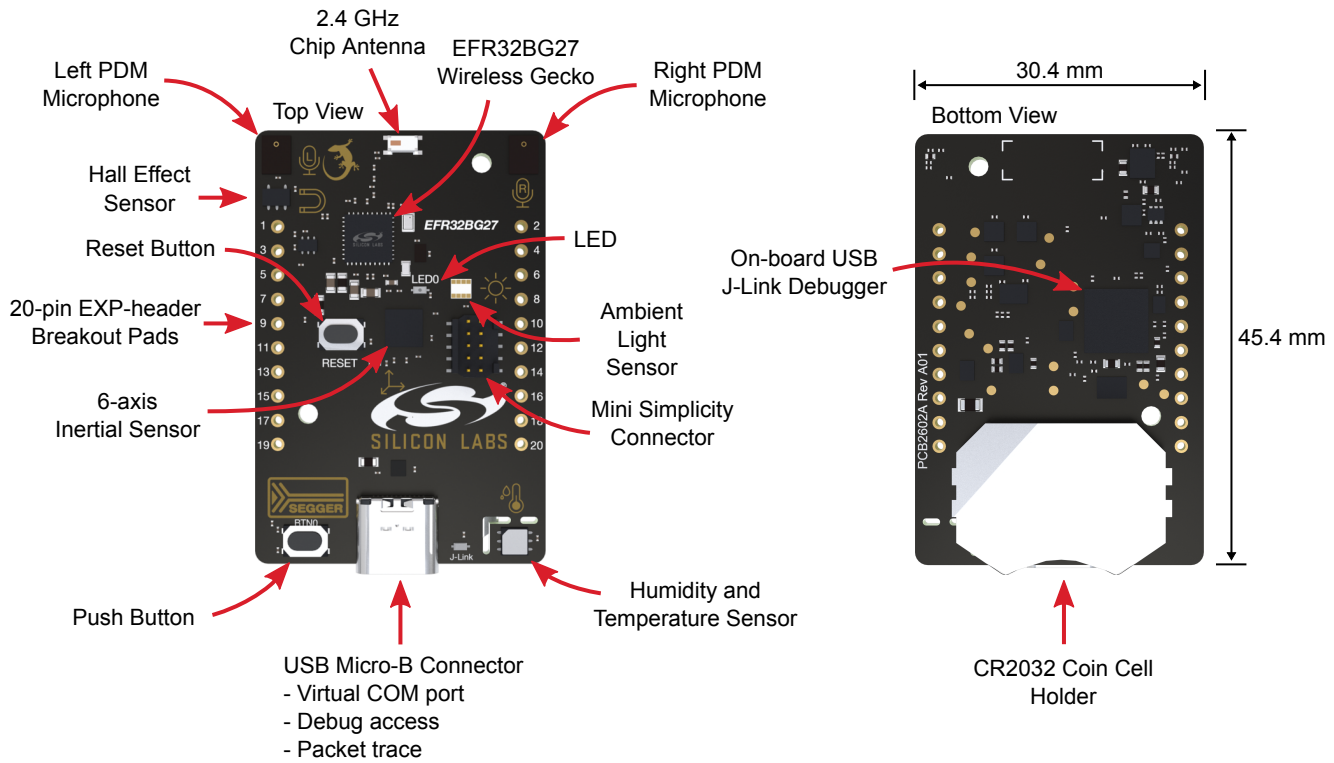


Figure 1.1. xG27 Dev Kit Hardware Layout

2. Specifications

2.1 Recommended Operating Conditions

The following table provides guidelines for correct use of the xG27 Dev Kit, indicating typical operating conditions and some design limits.

Table 2.1. Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
USB Supply Input Voltage	V_{USB}	—	5.0	—	V
Battery Supply Input Voltage	V_{VBAT}	2.0	3.0	3.3	V
Supply Input Voltage (VMCU supplied externally) ^{1,2}	V_{VMCU}	2.0	3.0	3.6	V
Operating Temperature	T_{OP}	—	20	—	°C

Note:

1. The maximum supply voltage may be less under certain conditions when using the EFR32BG27's dc-dc converter. For more information, see the EFR32BG27 data sheet.
2. Not recommended for use with rechargeable Lithium batteries. Most Li-Ion and Li-Po cells exceed 3.6 V when fully charged.

2.2 Current Consumption

The table below summarizes the data sheet current consumption of the various components on the board. The operating current of the board greatly depends on the application. The number of enabled sensors, how often they are sampled, and how often the radio is transmitting or receiving are examples of factors that influence the operating current. In many cases the given conditions differ from the operating conditions on the xG27 Dev Kit, but the table can still be used as an indication of how much each feature contributes to the total current consumption. More details can be found in the specific data sheet for each device.

Table 2.2. Current Consumption

Parameter	Symbol	Condition	Typ	Unit
EFR32BG27 Current Consumption ¹	I_{EFR32}	MCU current consumption in EM0 mode with all peripherals disabled (dc-dc converter at 3.0 V input and 1.8 V output, VSCALE1, 38.4 MHz crystal, CPU running Prime from flash at 25 °C)	30	μ A/MHz
		EM4, no BURTC, no LF oscillator	0.18	μ A
		Radio system current consumption in receive mode, active packet reception (dc-dc converter at 3.0 V input and 1.8 V output, MCU in EM1 and all MCU peripherals disabled, HCLK = 38.4 MHz, 1Mbit/s, 2GFSK, f = 2.4 GHz, VSCALE1 at 25 °C)	4	mA
		Radio system current consumption in transmit mode (dc-dc converter at 3.0 V input and 1.8 V output, MCU in EM1 and all MCU peripherals disabled, HCLK = 38.4 MHz, f = 2.4 GHz, CW, 8 dBm output power, VSCALE1 at 25 °C)	11.5	mA
Ambient Light Sensor Current Consumption ²	$I_{VEML6035}$	Shutdown at 1.8 V	0.5	μ A
		Operation mode at 1.8 V (ALS only)	170	μ A
RH/Temp Sensor Current Consumption ³	I_{Si7021}	Standby, -40 to +85 °C	0.06	μ A
		RH conversion in progress	150	μ A
		Temperature conversion in progress	90	μ A
		Peak I_{DD} during I ² C operations	3.5	mA
Hall Effect Magnetic Sensor Current Consumption ⁴	I_{DD}	Sleep mode at 3.3 V	50	nA
		Average current for periodic activation at 3.3 V, sleep timer enabled, 200 msec sleep time	0.4	μ A
		Conversion in progress at 3.3 V	5	mA
Microphone Current Consumption ⁵	I_{MIC}	Sleep mode current (Fclock = 0 Hz, VDD = 3.6 V)	26	μ A
		Supply current in performance mode (VDD = 3.6 V, Fclock = 2.4 MHz)	700	μ A
IMU Current Consumption ⁶	I_{IMU}	Full-chip sleep mode at 1.8 V supply	6	μ A
		Gyroscope only, 100 Hz update rate at 1.8 V supply	1.6	mA
		Accelerometer only, 100 Hz update rate at 1.8 V supply	57	μ A
		Gyroscope + Accelerometer, 100 Hz update rate at 1.8 V supply	1.9	mA
Serial Flash Memory Current Consumption ⁷	I_{Flash}	Deep power-down current in ultra-low-power mode at 1.8 V	0.007	μ A
		Standby current in ultra-low-power mode at 1.8 V	5	μ A
		Write status register current in ultra-low-power mode at 1.8 V	3.1	mA

Parameter	Symbol	Condition	Typ	Unit
On-board Debugger Sleep Current Consumption ⁸	I _{DBG}	On-board debugger current consumption when USB cable is not inserted (EFM32GG12 EM4S mode current consumption)	80	nA
Minimum Board Current Consumption	I _{BOARD}	Minimum total board current consumption for VMCU = 3.0 V with EFR32BG27 in EM4S, the USB cable disconnected, and all peripherals either in sleep mode or disconnected	0.4	μA

Note:

1. From EFM32BG27 data sheet
2. From VEML6035 data sheet
3. From Si7021-A20 data sheet
4. From Si7210 data sheet
5. From SPK0641HT4H-1 data sheet
6. From ICM-20648 data sheet
7. From MX25R8035F data sheet
8. From EFM32GG12 data sheet

3. Hardware

The core of the xG27 Dev Kit is the EFR32BG27 Wireless Gecko System-on-Chip. The board also contains several peripherals connected to the EFR32BG27. Refer to section 1.4 [Kit Hardware Layout](#) for hardware component placement and layout information.

3.1 Block Diagram

An overview of the xG27 Dev Kit is illustrated in the figure below.

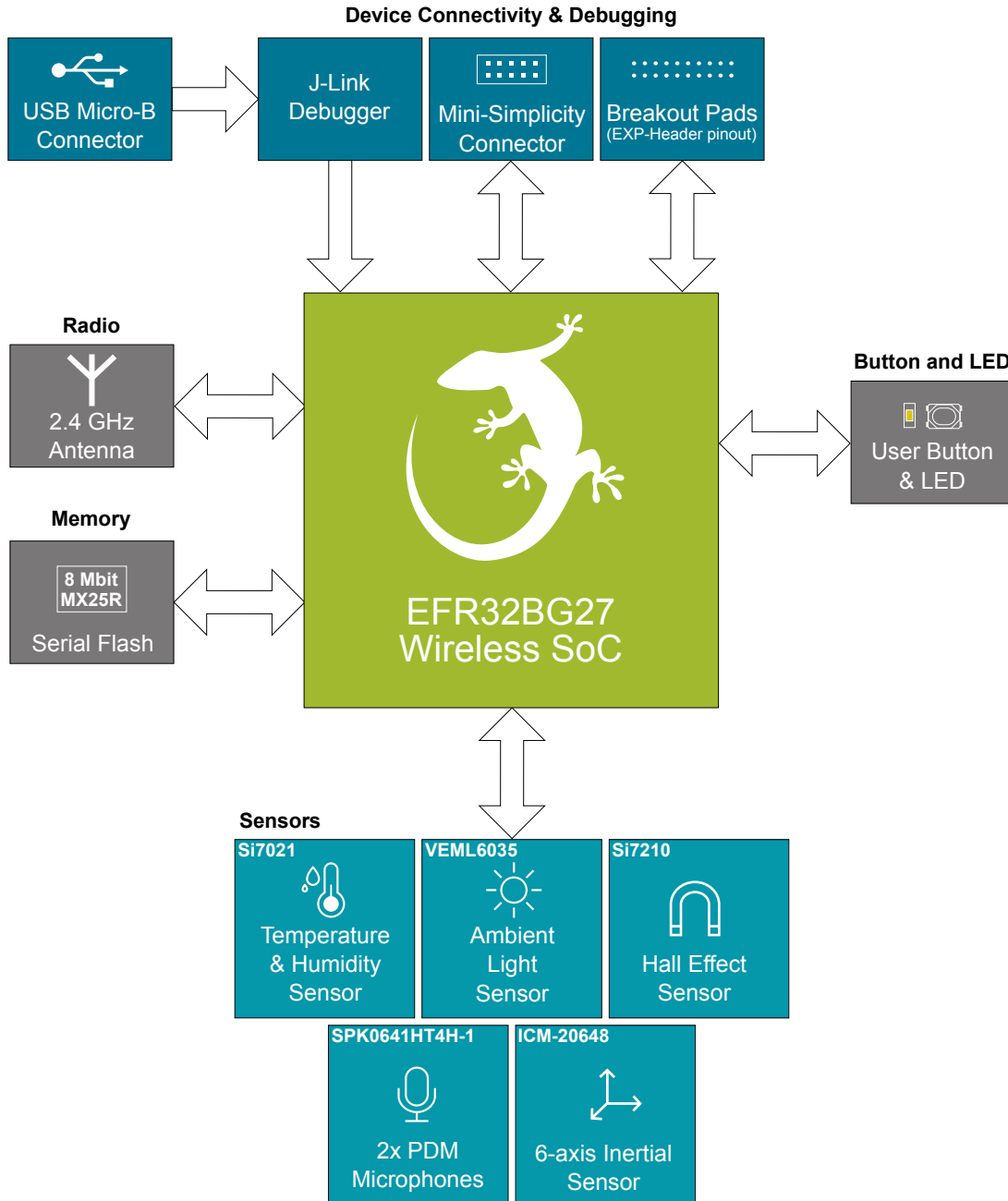


Figure 3.1. Kit Block Diagram

3.2 Power Supply

The kit can be powered through one of these interfaces:

- USB Type-C
- Battery
- Mini Simplicity connector

The figure below shows the power options available on the kit and illustrates the main system power architecture.

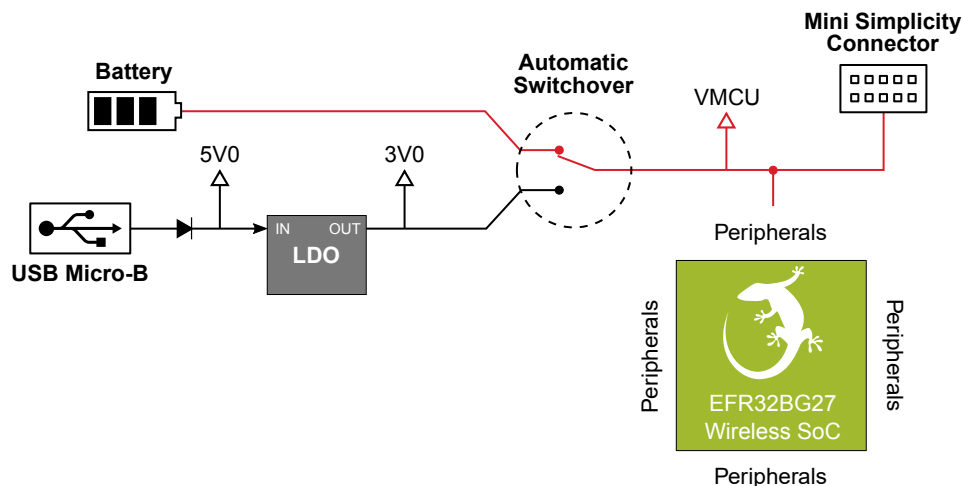


Figure 3.2. xG27 Dev Kit Power Architecture

Power is normally applied either through the USB cable or a CR2032 battery. When the USB cable is connected, VBUS is regulated down to 3.0 V. An automatic switchover circuit switches the main system power from battery power to USB power when the USB cable is inserted and protects the battery from reverse current.

Power can also be applied through the Mini Simplicity connector. This requires that no other power sources are present on the kit, as power is injected directly to the VMCU net. It is important to follow this process to avoid power conflicts and backfeeding the battery. Powering the xG27 Dev Kit through the Mini Simplicity connector allows current measurements using the Advanced Energy Monitoring (AEM) as described in section 4.2 External Debugger.

Important: When powering the board through the Mini Simplicity connector, the USB and battery power sources must be removed.

The power supply options are summarized in the table below.

Table 3.1. xG27 Dev Kit Power Options

Supply Mode	Typical Input Voltage	VMCU Source	3V0	5V
USB power	5.0 V	On-board regulator	On-board regulator	USB VBUS
CR2032 battery	3.0 V	Battery voltage	Disconnected	No voltage present
Mini Simplicity	3.3 V	Debugger dependent	Disconnected	No voltage present

3.3 EFR32BG27 Reset

The EFR32BG27 can be reset by a few different sources:

- A user pressing the RESET button.
- The on-board debugger pulling the #RESET pin low.
- An external debugger pulling the #RESET pin low.

3.4 Peripherals

The xG27 Dev Kit contains a set of peripherals that can be accessed from the EFR32BG27. All the peripherals have enable signals which can be used to completely turn off the peripherals that are not in use, or they can be put into a state that draws a minuscule amount of power. This allows for the lowest possible power consumption in every application. The following peripherals are accessible to the EFR32BG27:

- One Silicon Labs Si7021 relative humidity & temperature sensor
- One Silicon Labs Si7210 hall effect sensor
- One Vishay VEML6035 ambient light sensor
- One TDK InvenSense ICM-20648 6-axis inertial measurement sensor
- Two Knowles SPK0641HT4H-1 MEMS microphones with PDM output
- One Macronix MX25R8035F ultra-low-power 8 Mbit SPI flash
- One LED and one push button

The figure below gives an overview of the peripherals that are connected to the EFR32BG27. Note that some of the peripherals share the same interface and enable signals. As the enable signals do not have external pull-down resistors on the board, the application code should actively drive the signals either low or high to prevent the lines from floating.

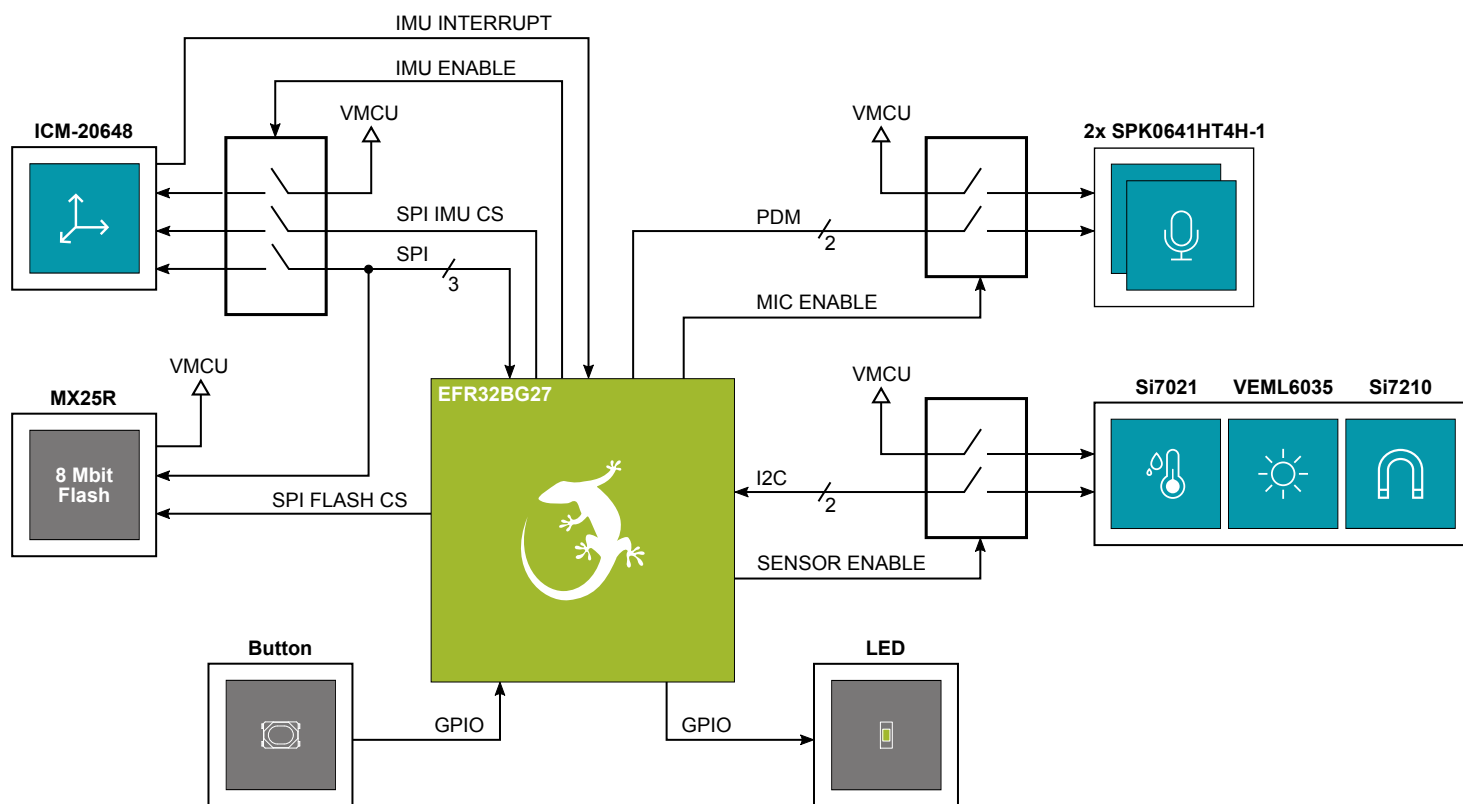


Figure 3.3. Peripherals

3.4.1 Si7021 Relative Humidity and Temperature Sensor

The Si7021 I²C relative humidity and temperature sensor is a monolithic CMOS IC integrating humidity and temperature sensor elements, an analog-to-digital converter, signal processing, calibration data, and an I²C interface. The patented use of industry-standard, low-K polymeric dielectrics for sensing humidity enables the construction of low-power, monolithic CMOS Sensor ICs with low drift and hysteresis, and excellent long term stability. The Si7021 offers an accurate, low-power, factory-calibrated digital solution ideal for measuring humidity, dew-point, and temperature in applications ranging from HVAC/R and asset tracking to industrial and consumer platforms.

On the xG27 Dev Kit, the Si7021 is connected through a switch. The switch must therefore be enabled by setting EFR32_SENSOR_EN high before it can be used by the application. This enables power to the Si7021 and connects the I²C lines used for the sensor to the EFR32BG27 I²C bus. The application code should always drive the EFR32_SENSOR_EN signal either high or low to prevent it from floating. The figure below shows how the Si7021 is connected to the EFR32BG27.

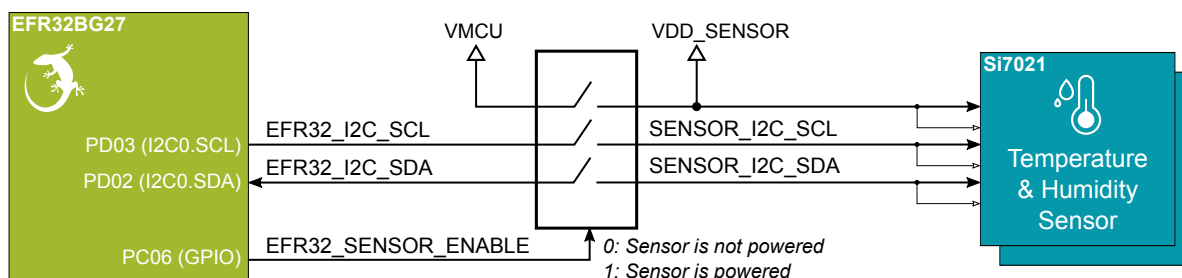


Figure 3.4. Si7021 Relative Humidity and Temperature Sensor

Although measures have been taken to thermally isolate the sensor from the board, temperature readings will be influenced when power is dissipated on the board. More accurate temperature measurements are achieved when powering the board with a battery or through the Mini Simplicity connector as self-heating from the on-board LDO is eliminated and the on-board debugger is put in a low-power state.

3.4.2 Si7210 Hall Effect Sensor

The Si7210 family of Hall effect sensors from Silicon Labs combines a chopper-stabilized Hall element with a low-noise analog amplifier, 13-bit analog-to-digital converter, and an I²C interface. Leveraging Silicon Labs' proven CMOS design techniques, the Si7210 family incorporates digital signal processing to provide precise compensation for temperature and offset drift. The 13-bit magnetic field strength can be read through the I²C interface at any time. Applications for the Si7210 include mechanical position sensing in consumer, industrial, and automotive applications, reed switch replacement, fluid level measurement, speed sensing, and control knobs, and switches.

On the xG27 Dev Kit, the Si7210 is connected through a switch. The switch must therefore be enabled by setting EFR32_SENSOR_EN high before it can be used by the application. This enables power to the Si7210 and connects the I²C lines used for the sensor to the EFR32BG27 I²C bus. The application code should always drive the EFR32_SENSOR_EN signal either high or low to prevent it from floating. The figure below shows how the Si7210 is connected to the EFR32BG27.

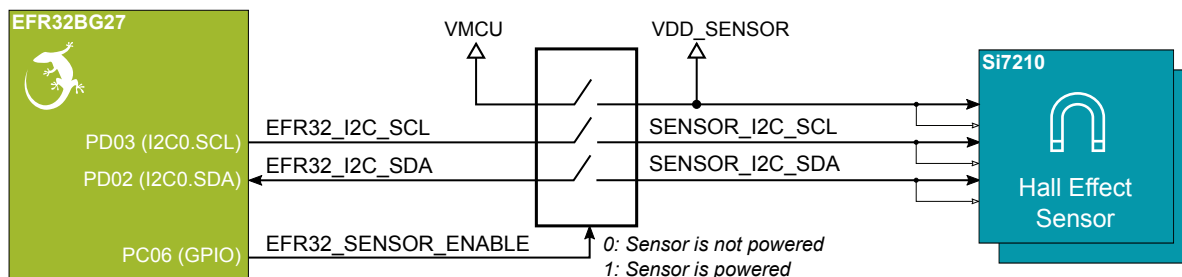


Figure 3.5. Hall Effect Sensor

3.4.3 VEML6035 Ambient Light Sensor

The VEML6035 is an ambient light sensor with I²C digital interface.

On the xG27 Dev Kit, the VEML6035 is connected through a switch. The switch must therefore be enabled by setting EFR32_SENSOR_EN high before it can be used by the application. This enables power to the VEML6035 and connects the I²C lines used for the sensor to the EFR32BG27 I²C bus. The application code should always drive the EFR32_SENSOR_EN signal either high or low to prevent it from floating. The figure below shows how the VEML6035 is connected to the EFR32BG27.

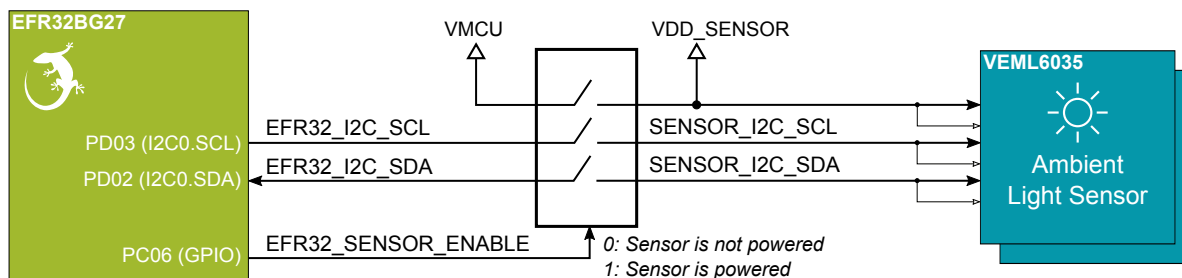


Figure 3.6. VEML6035 Ambient Light Sensor

3.4.4 PDM Stereo Microphones

The xG27 Dev Kit features two Knowles SPK0641HT4H-1 digital MEMS microphones with PDM output. The microphones are configured to form a stereo sound input device using only a single PDM data line. The clock to the microphones are fed from a pin on EFR32BG27 with PDM clock support. The output from both microphones are connected to the same line and connected to a pin on the EFR32BG27 supporting PDM data input.

On the xG27 Dev Kit, the microphones are connected through a switch. The switch must therefore be enabled by setting EFR32_MIC_EN high before it can be used by the application. This enables power to the microphones and connects the PDM lines used for the sensor to the EFR32BG27. The application code should always drive the EFR32_MIC_EN signal either high or low to prevent it from floating. The figure below shows how the microphones are connected to the EFR32BG27.

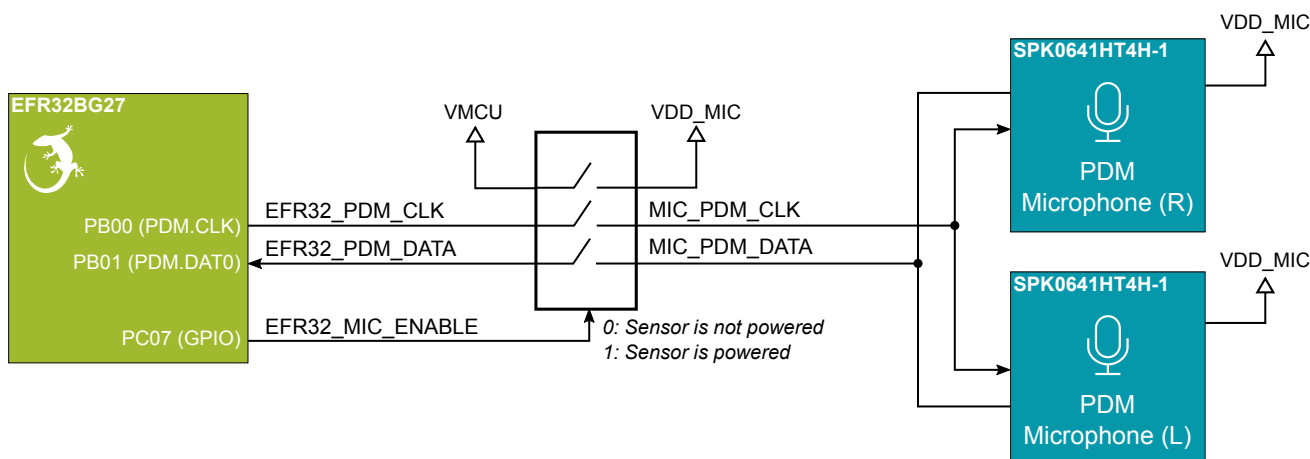


Figure 3.7. Digital Stereo Microphones

3.4.5 ICM-20648 6-Axis Inertial Sensor

The ICM-20648 is a 6-axis inertial sensor consisting of a 3-axis gyroscope and a 3-axis accelerometer. The sensor detects acceleration and angular rate in and around the X-, Y- and Z-axes with integrated 16-bit ADCs and programmable digital filters.

On the xG27 Dev Kit, the ICM-20648 is connected through a switch. The switch must be enabled by setting EFR32_IMU_EN high before it can be used by the application. This enables power to the ICM-20648 and connects the SPI lines used for the sensor to the EFR32BG27 SPI bus. The application code should always drive the EFR32_IMU_EN signal either high or low to prevent it from floating. Note the presence of the external pull-up resistor on the interrupt line as this can cause back powering if not handled correctly in software. The figure below shows how the ICM-20648 is connected to the EFR32BG27.

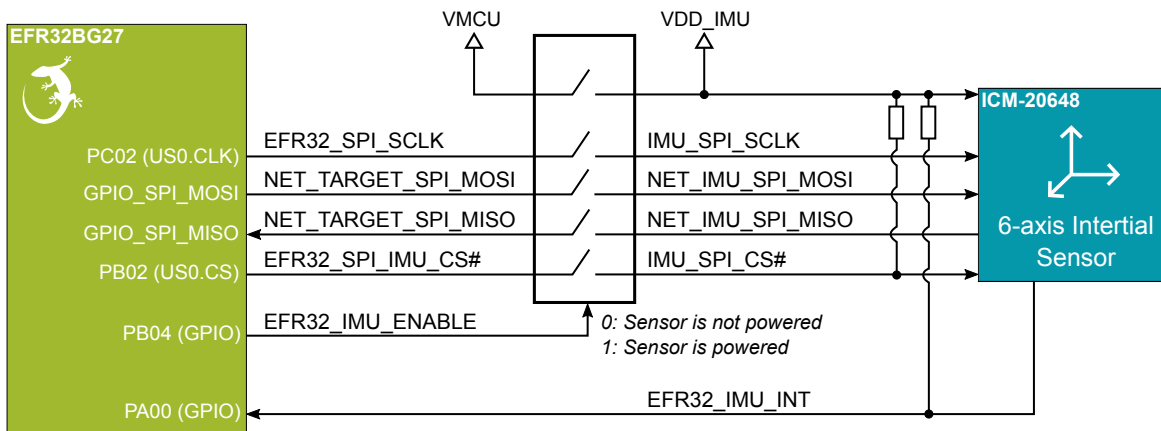


Figure 3.8. ICM-20648 Six-axis Inertial Sensor

The inertial sensor is located close to the geometrical center of the board. The coordinate system and rotation of the sensor follows the right-hand rule, and the spatial orientation of the board is shown in the figure below.

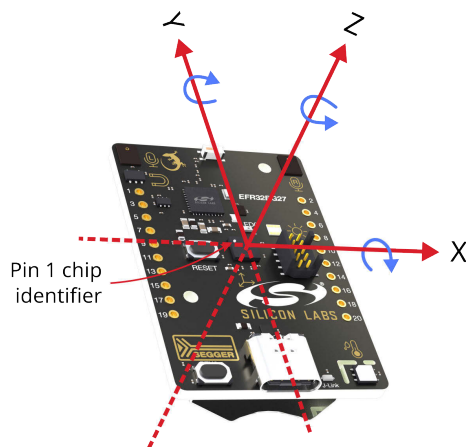


Figure 3.9. xG27 Dev Kit Spatial Orientation

3.4.6 Push Button and LED

The kit has one user push button, marked BTN0, that is connected to a GPIO on the EFR32BG27. The button is connected to pin PB03 and it is debounced by an RC filter with a time constant of 1 ms. The logic state of the button is high while the button is not being pressed, and low when the button is pressed.

The kit also features one yellow LED, marked LED0, that is controlled by a GPIO pin on the EFR32BG27. The LED is connected to pin PA04 in an active-high configuration.

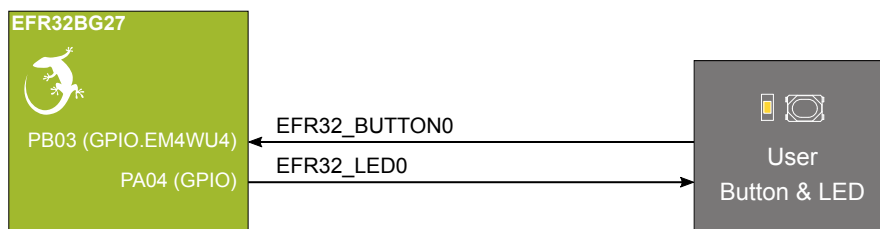


Figure 3.10. Button and LED

3.4.6.1 GPIOs on Unused JTAG Debug Pins

The EFR32BG27 allows the PA04 pin, which is connected to TDI on the JTAG Debug Port, to be used for other purposes if JTAG is not used. The xG27 Dev Kit uses SWD as debugging interface and the PA04 pin of the EFR32BG27 is used to control LED0. Under certain circumstances, such as an unexpected reset during a debug session, control of the PA04 pin can be transferred to the debug port which will result in the user application losing control of the PA04 pin. If this happens, known workarounds are to disconnect all active debug sessions and then reset the EFR32BG27 through either the reset pin or by toggling the power.

3.4.7 External Memory

The xG27 Dev Kit includes an 8 Mbit Macronix SPI Flash that is connected directly to the EFR32BG27. The MX25R series are ultra-low power serial flash devices, so there is no need for a separate enable switch to keep current consumption down. However, it is important that the flash is always put in deep power down mode when not used. This is done by issuing a command over the SPI interface. In deep power down, the MX25R typically adds approximately 100 nA to the current consumption. The figure below shows how the serial flash is connected to the EFR32BG27.

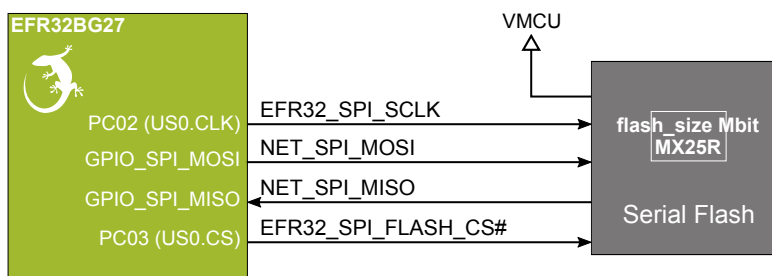


Figure 3.11. Serial Flash

3.5 On-board Debugger

The xG27 Dev Kit contains a microcontroller separate from the EFR32BG27 Wireless Gecko that provides the user with an on-board J-Link debugger through the USB Type-C port. This microcontroller is referred to as the "on-board debugger" and is not programmable by the user. When the USB cable is removed, the on-board debugger goes into a very low power shutoff mode (EM4S).

In addition to providing code download and debug features, the on-board debugger also presents a virtual COM port for general purpose application serial data transfer. The Packet Trace Interface (PTI) is also supported which offers invaluable debug information about transmitted and received packets in wireless links.

The figure below shows the connections between the target EFR32BG27 device and the on-board debugger. The figure also shows the Mini Simplicity Connector, and how this is connected to the same I/O pins.

Refer to section 4. [Debugging](#) for more details on debugging.

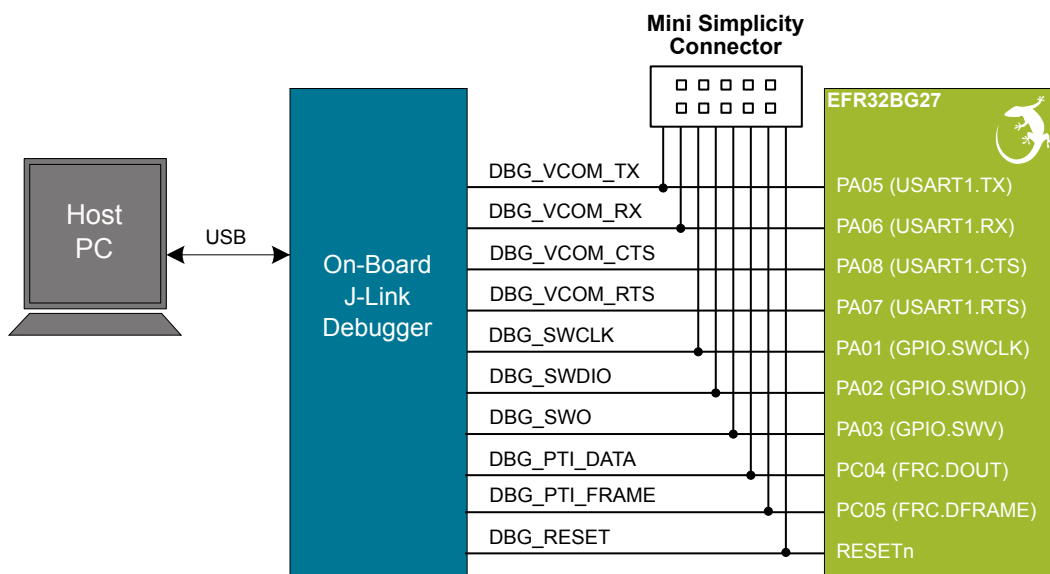


Figure 3.12. On-Board Debugger Connections

3.6 Connectors

The xG27 Dev Kit features a Mini Simplicity Connector, a USB Type-C connector, and 20 breakout pads that follow the EXP header pinout. The connectors are placed on the top side of the board, and their placement and pinout are shown in the figure below. For additional information on the connectors, see the following sub-chapters.

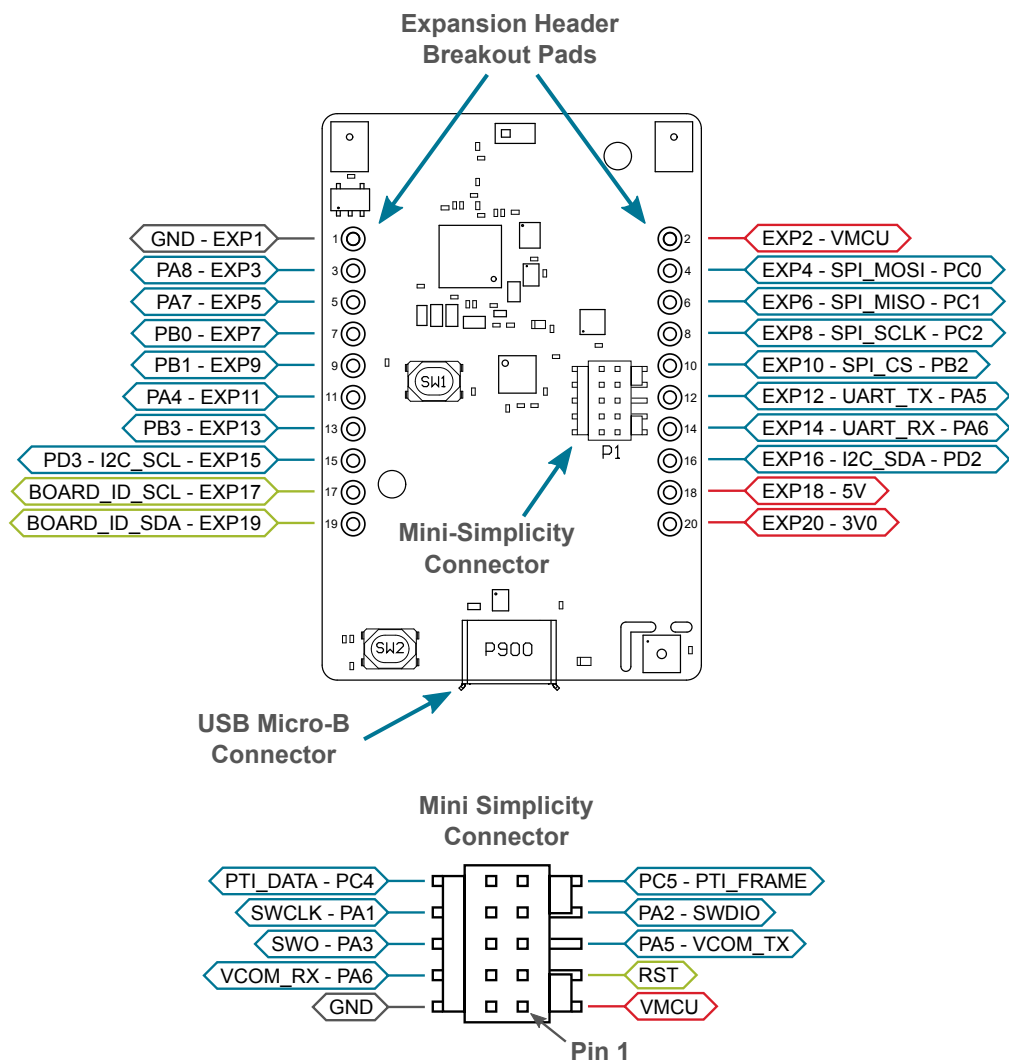


Figure 3.13. xG27 Dev Kit Connectors

3.6.1 Breakout Pads

Twenty breakout pads, which follow the EXP header pinout, are provided and allow connection of peripherals or add-on boards. Ten of the pads are located along the left side of the board and ten are located on the right side. The breakout pads expose I/O pins that can be used with most of the EFR32BG27's features. Additionally, the VMCU (main power rail), 3V0 (LDO regulator output), and 5V power rails are also exposed.

The breakout pads are pinned out similar to the EXP header found on other Silicon Labs Starter Kits, which ensures that commonly used peripherals such as SPI, UART, and I²C buses are available on fixed locations. The rest of the pins are used for general purpose IO. The EXP header allows the definition of EXP boards that can plug into a number of different Silicon Labs starter kits.

The pin-routing on EFR32 is very flexible, so most peripherals can be routed to any pin. However, pins may be shared between the breakout pads and other functions on the xG27 Dev Kit. The table below includes an overview of the EXP header and functionality that is shared with the kit.

Table 3.2. Expansion Header Pinout

Pin	Connection	EXP Header Function	Shared Feature
Right-side Breakout Pins			
2	VMCU	EFR32BG27 voltage domain, included in AEM measurements.	
4	PC00	SPI_COPI	IMU & Flash
6	PC01	SPI_CIPO	IMU & Flash
8	PC02	SPI_SCLK	IMU & Flash
10	PB02	SPI_CS	IMU
12	PA05	UART_TX	Virtual COM Port
14	PA06	UART_RX	Virtual COM Port
16	PD02	I2C_SDA	Sensor I2C bus
18	5V	Board USB voltage	
20	3V0	Board controller supply	
Left-side Breakout Pins			
1	GND	Ground	
3	PA08	GPIO	Virtual COM Port
5	PA07	GPIO	Virtual COM Port
7	PB00	GPIO	PDM Microphones
9	PB01	GPIO	PDM Microphones
11	PA04	GPIO	LED
13	PB03	GPIO	Button
15	PD03	I2C_SCL	Sensor I2C bus
17	BOARD_ID_SCL	Connected to Board Controller for identification of add-on boards.	
19	BOARD_ID_SDA	Connected to Board Controller for identification of add-on boards.	

3.6.2 Mini Simplicity Connector

The Mini Simplicity connector is a 10-pin, 1.27 mm pitch connector that allows the use of an external debugger such as the one found on a Silicon Labs Wireless Starter Kit mainboard. See section [4.2 External Debugger](#) for more details. The pinout of the connector on the board is described in the table below with the names being referenced from the EFR32BG27.

Table 3.3. Mini Simplicity Connector Pin Descriptions

Pin number	Function	Connection	Description
1	AEM	VMCU	Target voltage on the debugged application. May be supplied and monitored by the AEM on an external debugger.
2	GND	GND	Ground
3	RST	RESET	EFR32BG27 reset
4	VCOM_RX	PA06	Virtual COM Rx
5	VCOM_TX	PA05	Virtual COM Tx
6	SWO	PA03	Serial Wire Output
7	SWDIO	PA02	Serial Wire Data
8	SWCLK	PA01	Serial Wire Clock
9	PTI_FRAME	PC05	Packet Trace Frame
10	PTI_DATA	PC04	Packet Trace Data

3.6.3 Debug USB Type-C Connector

The debug USB port can be used for uploading code, debugging, and as a Virtual COM port. More information is available in section [4. Debugging](#).

4. Debugging

The xG27 Dev Kit contains an on-board SEGGER J-Link Debugger that interfaces to the target EFR32BG27 using the Serial Wire Debug (SWD) interface. The debugger allows the user to download code and debug applications running in the target EFR32BG27. Additionally, it also provides a VCOM port to the host computer that is connected to the target device's serial port for general purpose communication between the running application and the host computer. The Packet Trace Interface (PTI) is also supported by the on-board debugger which offers invaluable debug information about transmitted and received packets in wireless links. The on-board debugger is accessible through the USB Type-C connector.

An external debugger can be used instead of the on-board debugger by connecting it to the Mini Simplicity Connector. This allows advanced debugging features as described in section 4.2 External Debugger. When using an external debugger it is very important to make sure that there is no power source present on the xG27 Dev Kit, as the external debugger might source a voltage on the target power domain (VMCU).

Important: When connecting an external debugger that sources voltage to the VMCU net, the USB cable and battery must be removed from the xG27 Dev Kit. Failure to do so will create power conflicts.

The figure below shows the possible debug options.

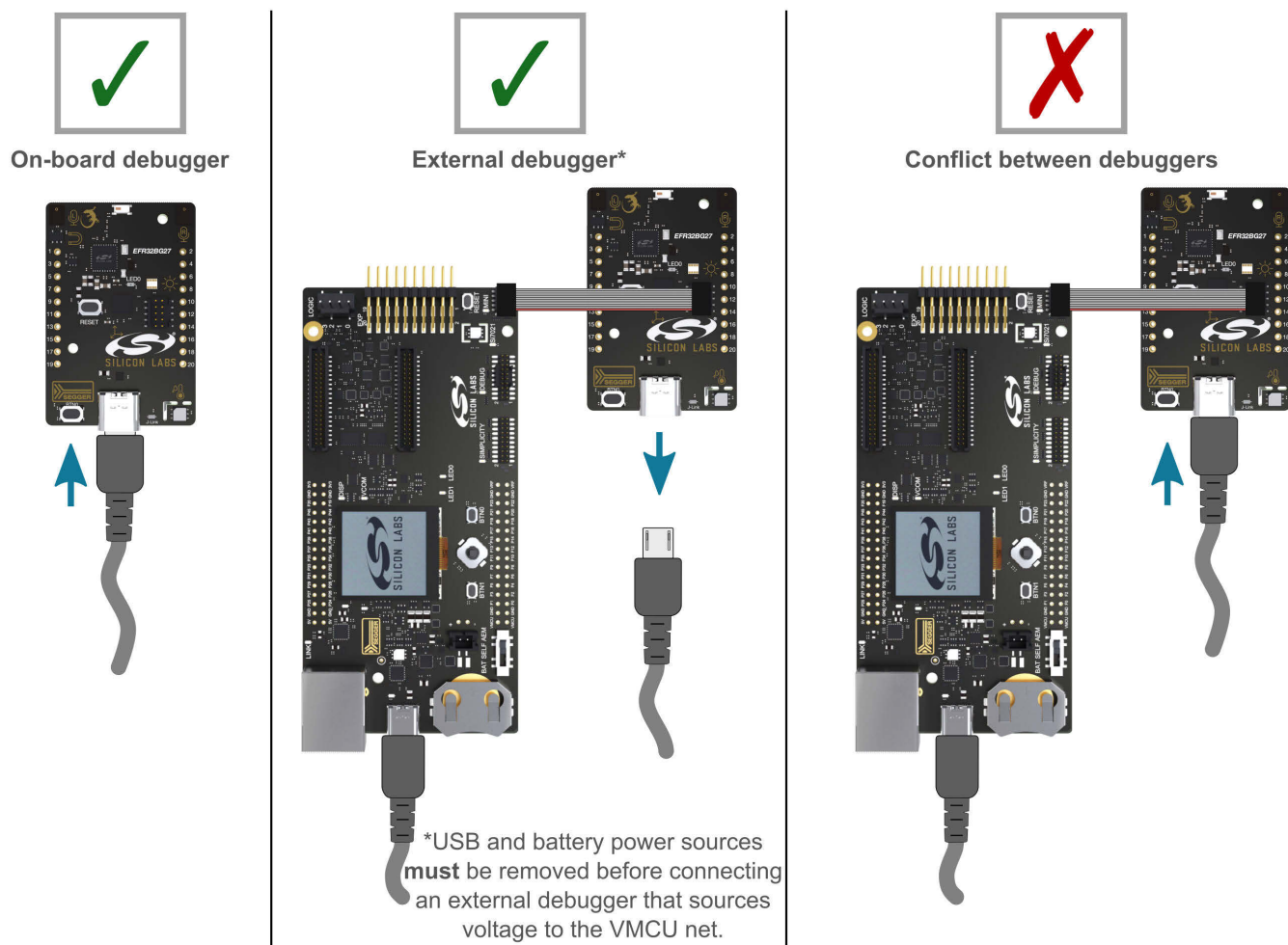


Figure 4.1. xG27 Dev Kit Debugging Possibilities

4.1 On-board Debugger

The on-board debugger is a SEGGER J-Link debugger running on an EFM32 Giant Gecko. The debugger is directly connected to the debug and VCOM pins of the target EFR32BG27.

When the debug USB cable is inserted, the on-board debugger is automatically activated, and takes control of the debug and VCOM interfaces. This means that debug and communication will **not** work with an external debugger connected at the same time. The on-board LDO is also activated, providing power to the board.

When the USB cable is removed, the board might still be running on battery power, as described in section . In this case, the on-board debugger goes into a very low power shutoff mode (EM4S), consuming about 80 nA. This means that battery lifetime will not be affected too much by the on-board debugger power consumption. Since the I/O voltage rail of the debugger remains powered in the battery operated mode, the pins connected to the debug and VCOM interfaces maintain proper isolation and prevent leakage currents.

4.2 External Debugger

A Wireless mainboard from Silicon Labs can be connected to the Mini Simplicity Connector and used for debugging instead of the on-board debugger. For instruction on using the mainboard for debugging, see [AN958: Debugging and Programming Interfaces for Custom Designs](#). Note that the Wireless STK Mainboard (BRD4001A) requires a BRD8010A STK/WSTK Debug Adapter to get access to the Mini Simplicity Connector. Debugging with an external Wireless mainboard gives access to the following debugging features:

- Debugging of the target device through SWD
- Communication using the VCOM port
- Packet Trace Interface (for wireless devices only)
- Advanced Energy Monitor

Note that the Mini Simplicity Connector **cannot** be used at the same time that the on-board debugger is active (USB cable is plugged in). For information on how to correctly connect to the kit, see [Figure 4.1 xG27 Dev Kit Debugging Possibilities on page 20](#).

Powering the board when using the Mini Simplicity Connector with a Wireless mainboard can be done using the AEM voltage supply of the Wireless mainboard. When doing this, remove both the USB cable and the coin cell battery from the xG27 Dev Kit before connecting the Wireless mainboard to the Mini Simplicity Connector. The power switch on the Wireless mainboard should be set in "AEM". Power-cycling of the board, if necessary, is easily done by flipping the power switch on the Wireless to "BAT" and back to "AEM", assuming a battery is not inserted in the Wireless mainboard.

It is possible to have the xG27 Dev Kit powered by a battery and still use the Mini Simplicity Connector with a Wireless mainboard for debugging and communication. In this case, the power switch on the Wireless mainboard must be set to the "BAT" position and the coin cell battery on the Wireless mainboard must be removed. In this case, level shifters on the Wireless mainboard itself take care of interfacing to different voltage levels on the xG27 Dev Kit. Connecting the board to an external debugger in other ways than those described above might create power conflicts, compromise the ability to monitor power consumption, and hazardously feed power back to the on-board battery.

Important: Always remove the battery if you are not sure whether the external debugger is sourcing voltage to xG27 Dev Kit.

4.3 Virtual COM Port

The virtual COM port (VCOM) is a connection to a UART on the EFR32BG27 and allows serial data to be sent and received from the device. The on-board debugger presents this connection as a virtual COM port on the host computer that shows up when the USB cable is inserted.

Data is transferred between the host computer and the debugger through the USB connection, which emulates a serial port using the USB Communication Device Class (CDC). From the debugger, the data is passed on to the target device through a physical UART connection.

The serial format is 115200 bps, 8 bits, no parity, and 1 stop bit by default.

Note: Changing the baud rate for the COM port on the PC side does not influence the UART baud rate between the debugger and the target device. However, it is possible to change the VCOM baud rate through the kits' Admin Console available through Simplicity Studio.

Alternatively, the VCOM port can also be used through the Mini Simplicity Connector with an external Wireless mainboard. Using the VCOM port through the Mini Simplicity Connector with an external Wireless mainboard works in a similar way, but requires that the USB cable to the on-board debugger is unplugged. The board controller on the Wireless mainboard then makes the data available over USB (CDC) or an IP socket. Flow control is not available over the Mini Simplicity Connector.

5. Radio

5.1 RF Section

This section gives a short introduction to the RF section of the BRD2602A board.

The schematic of the RF section is shown in the figure below.

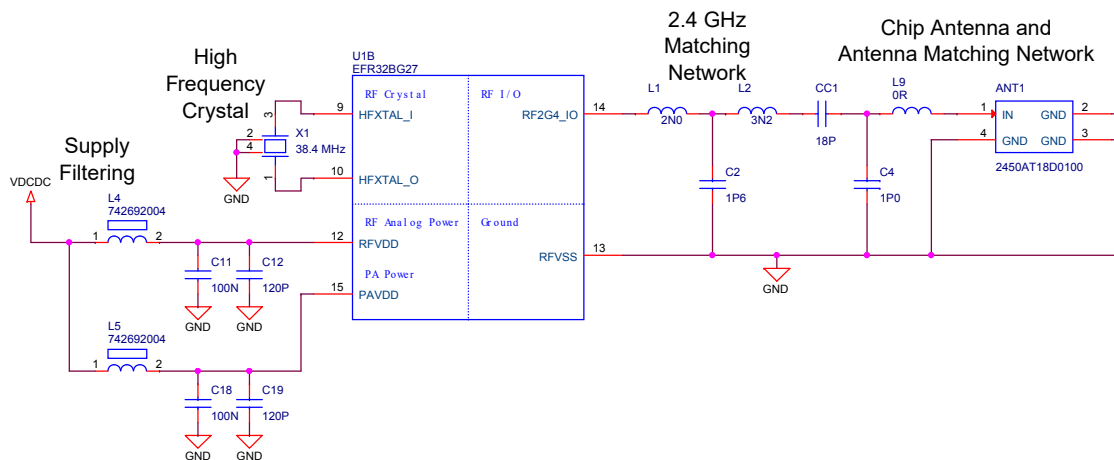


Figure 5.1. Schematic of the RF section

5.1.1 Description of the RF Matching

The EFR32BG27 RF port impedance is matched to 50 Ohm: the RF2G4_IO pin is connected to a three-element impedance matching and harmonic filter circuitry and a dc blocking capacitor. The on-board ceramic antenna is also matched to 50 Ohm by its impedance matching components and connected to the EFR32BG27.

5.1.2 RF Section Power Supply

On the BRD2602A, the supply for the radio (RFVDD) and the power amplifier (PAVDD) is connected to the on-chip dc-dc converter. By default, the dc-dc converter provides 1.8 V for the entire RF section (for details, see the schematic of the BRD2602A).

5.1.3 RF Matching Bill of Materials

The Bill of Materials of the BRD2602A RF matching network is shown in the following table.

Table 5.1. Bill of Materials of the BRD2602A RF Matching Network

Component name	Value	Manufacturer	Part Number
L1	2.0 nH	Murata	LQP03TN2N0C02D
L2	3.2 nH	Murata	LQP03TN3N2C02D
C2	1.6 pF	Murata	GRM0335C1H1R6WA01D
CC1	18 pF	Murata	GJM0335C1E180GB01D

5.1.4 Antenna

The BRD2602A has an on-board ceramic antenna.

The land pattern for the antenna on the PCB layout was designed based on the recommendations of the antenna data sheet. Because there is a significant difference between the layout (practically the board size) of the BRD2602A and the antenna evaluation board, the applied antenna matching network deviates from the recommendation.

The values of the antenna matching network components were fine-tuned to match the antenna impedance close to 50 Ohm on the BRD2602A PCB. The resulting antenna impedance and reflection are shown in the figure below.

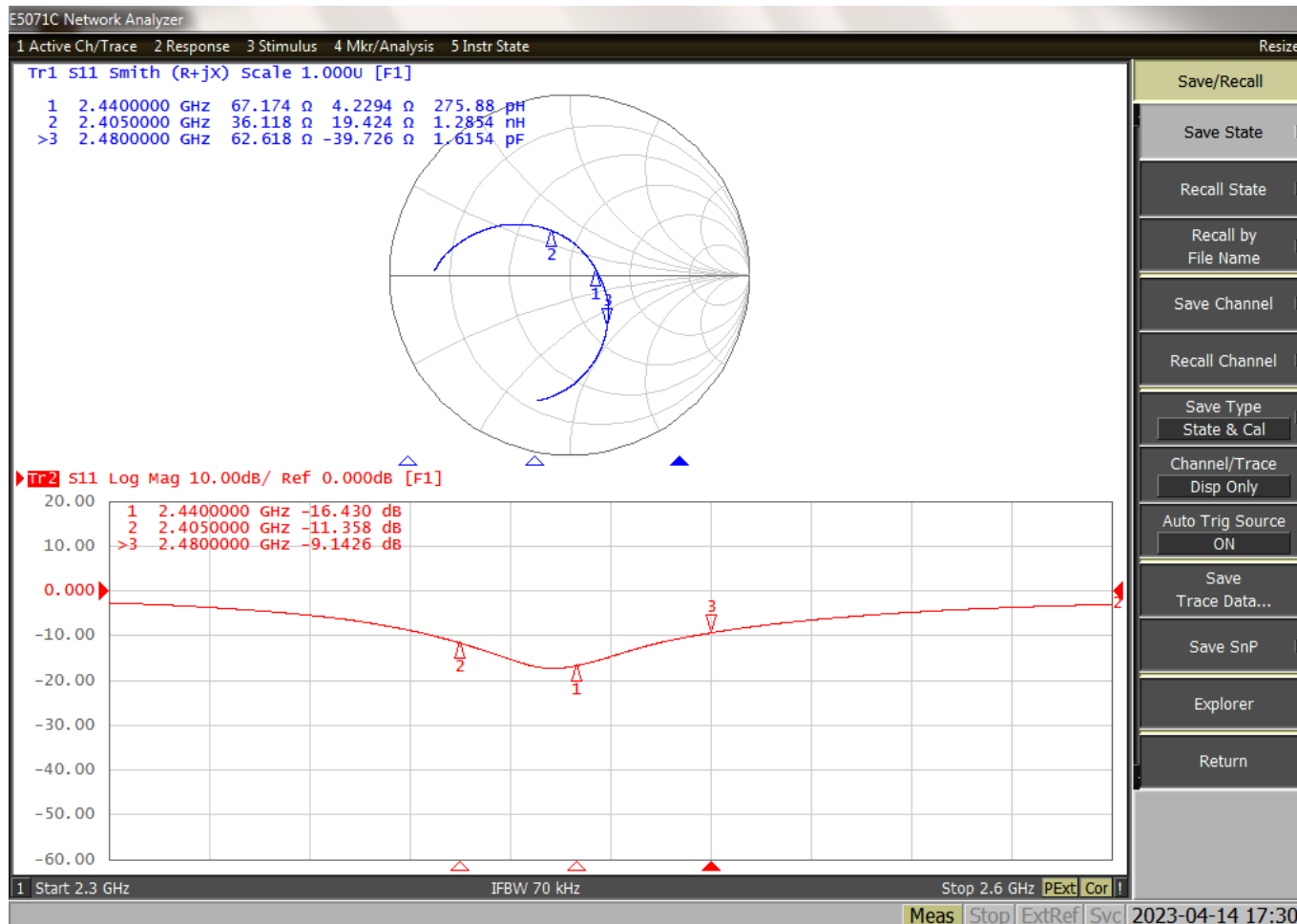


Figure 5.2. Fine-tuned Antenna Impedance (Blue Curve) and Reflection (Red Curve)

5.1.5 Antenna Matching Bill of Materials

The Bill of Materials of the BRD2602A antenna matching network is shown in the following table.

Table 5.2. Bill of Materials of the BRD2602A Antenna Matching Network

Component name	Value	Manufacturer	Part Number
ANT1	—	Johanson	2450AT18D0100
L9	0 Ohm	—	—
C5	1.0 pF	Murata	GRM0335C1E1R0BA01D

5.2 EMC Regulations for 2.4 GHz

5.2.1 ETSI EN 300-328 Emission Limits for the 2400-2483.5 MHz Band

Based on ETSI EN 300-328, the allowed maximum fundamental power for the 2400-2483.5 MHz band is 20 dBm EIRP. For the unwanted emissions in the 1 GHz to 12.75 GHz domain the specified limit is -30 dBm EIRP.

5.2.2 FCC15.247 Emission Limits for the 2400-2483.5 MHz Band

FCC 15.247 allows conducted output power up to 1 Watt (30 dBm) in the 2400-2483.5 MHz band. For spurious emissions the limit is -20 dBc based on either conducted or radiated measurement, if the emission is not in a restricted band. The restricted bands are specified in FCC 15.205. In these bands the spurious emission levels must meet the levels set out in FCC 15.209. In the range from 960 MHz to the frequency of the 5th harmonic, it is defined as 0.5 mV/m at 3 m distance (equals to -41.2 dBm in EIRP).

If of operating in the 2400-2483.5 MHz band, the 2nd, 3rd, and 5th harmonics can fall into restricted bands, so for those the -41.2 dBm limit should be applied. For the 4th harmonic, the -20 dBc limit should be applied.

5.2.3 Applied Emission Limits

The overall applied limits are shown in the table below. For the harmonics that fall into the FCC restricted bands, the FCC 15.209 limit is applied, and the ETSI EN 300-328 limit is applied for the rest.

Table 5.3. Applied Limits for Spurious Emissions

Harmonic	Frequency	Limit
2nd	4800~4967 MHz	-41.2 dBm
3rd	7200~7450.5 MHz	-41.2 dBm
4th	9600~9934 MHz	-30 dBm
5th	12000~12417.5 MHz	-41.2 dBm

5.3 Relaxation with Modulated Carrier

Depending on the applied modulation scheme and the Spectrum Analyzer settings specified by the relevant EMC regulations, the measured power levels are usually lower compared to the results with an unmodulated carrier. These differences have been measured and used as relaxation factors on the results of the radiated measurement performed with an unmodulated carrier. With this method, the radiated compliance with modulated transmission can be evaluated.

In this case, both the ETSI EN 300-328 and the FCC 15.247 regulations define the following Spectrum Analyzer settings for measuring the unwanted emissions above 1 GHz:

- Detector: Average
- RBW: 1 MHz

The table below shows the relative levels of the measured modulated signals compared to the unmodulated levels with the above Spectrum Analyzer settings in case of the supported modulation schemes.

Table 5.4. Measured Relaxation Factors for the Supported Modulation Schemes

Applied Modulation (Packet Length: 255 bytes)	BLE Coded PHY: 125 Kb/s (PRBS9) [dB]	BLE Coded PHY: 500 Kb/s (PRBS9) [dB]	BLE 1M PHY: 1 Mb/s (PRBS9) [dB]	BLE 2M PHY: 2 Mb/s (PRBS9) [dB]
2nd harmonic	-2.7	-3.1	-3.3	-9.1
3rd harmonic	-4.8	-5.2	-5.2	-10.7
4th harmonic	-5.5	-6.5	-6.7	-11.9
5th harmonic	-6.3	-6.5	-6.7	-11.4

As it can be observed, the BLE 125 Kb/s coded modulation scheme has the lowest relaxation factors. These values will be used as the worst-case relaxation factors for the radiated measurements.

5.4 Radiated Power Measurements

The output power of the EFR32BG27 was set to 8 dBm. The board was supplied through its USB connector by connecting to a PC through a USB cable.

During the measurements, the board was rotated in three cuts; see the reference plane illustration in the figure below. The radiated powers of the fundamental and the harmonics were measured with horizontal and vertical reference antenna polarizations.

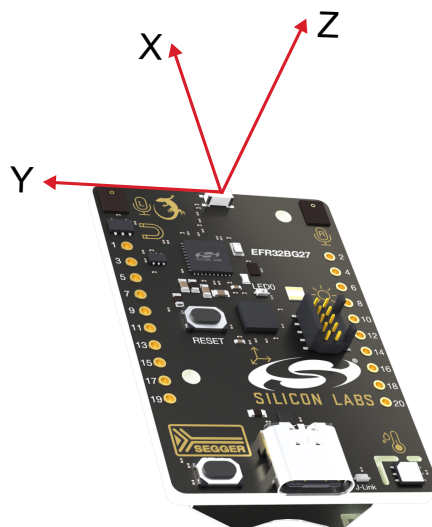


Figure 5.3. DUT Reference Planes

5.4.1 Maximum Radiated Power Measurement

The transceiver was operated in unmodulated carrier transmission mode, and the output power of the radio was set to 8 dBm. The results are shown in the table below.

The correction factors are applied based on the BLE 125 Kb/s coded modulation, showed in section 5.3 Relaxation with Modulated Carrier. The correction factors are larger for the rest of the supported modulation schemes; thus, the related calculated margins would be higher than those shown in the table below. Thus, the below margins can be considered as worst-case margins.

Table 5.5. Maximums of the Measured Radiated Powers of BRD2602A

Frequency (2440 MHz)	Measured Un-modulated EIRP [dBm]	Orientation	BLE 125 Kb/s Coded Modulation			Limit in EIRP [dBm]
			Correction Factor [dB]	Calculated Modulated EIRP [dBm]	Modulated Margin [dB]	
Fund	9.5	YZ/H	NA (0 is used)	7.3	22.7	30
2nd	-57.8	YZ/H	-2.7	-60.5	19.3	-41.2
3rd	-46.3	YZ/H	-4.8	-51.1	9.9	-41.2
4th	<-50*	—	-5.5	—	>20	-30
5th	-49.9	YZ/V	-6.3	-56.2	15.0	-41.2

* Signal level is below the Spectrum Analyzer noise floor.

As shown in the above table, the radiated power levels with modulation are far below the applied limits.

5.4.2 Antenna Pattern Measurement

The measured typical antenna patterns are shown in the figures below.

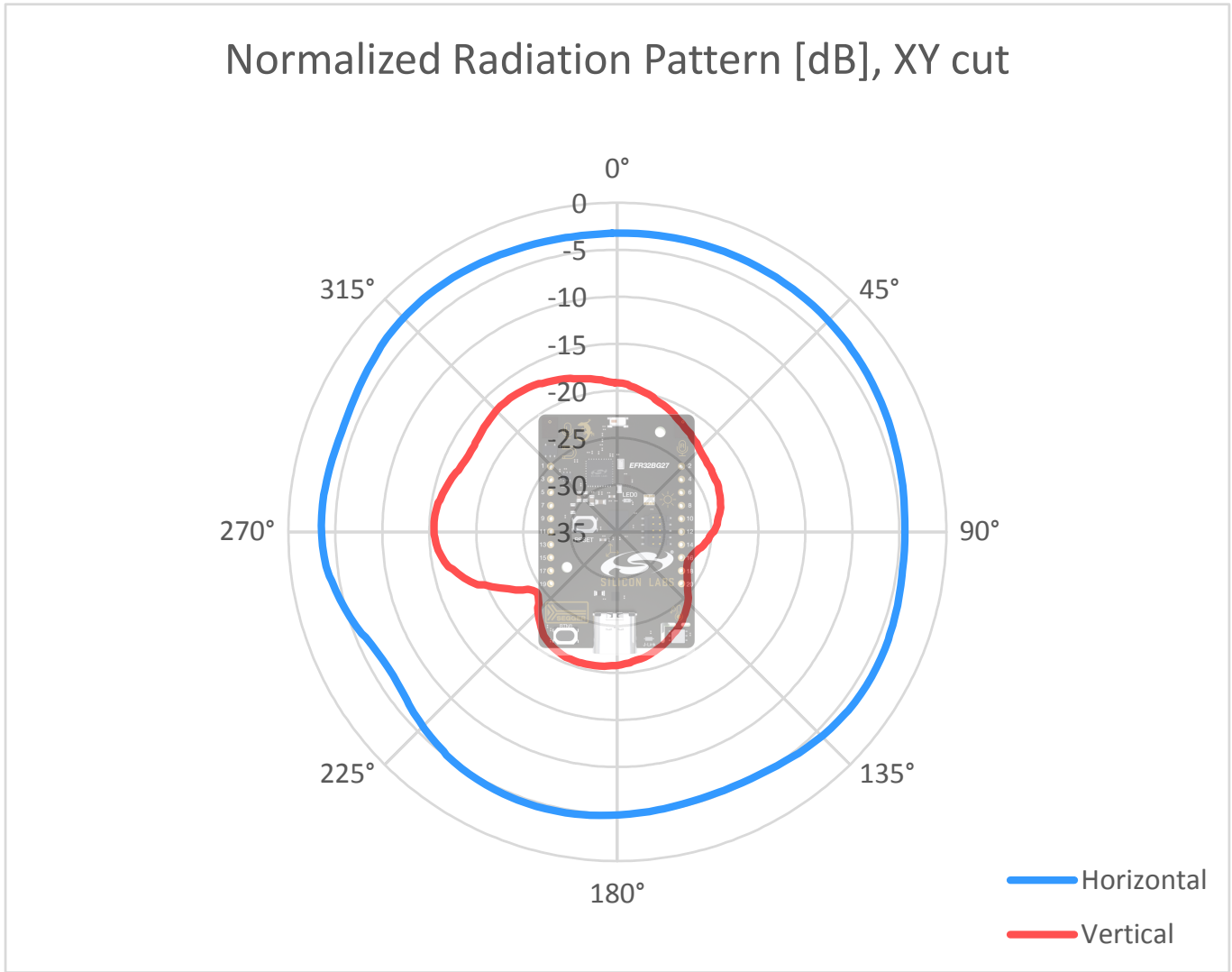


Figure 5.4. Antenna Pattern - XY

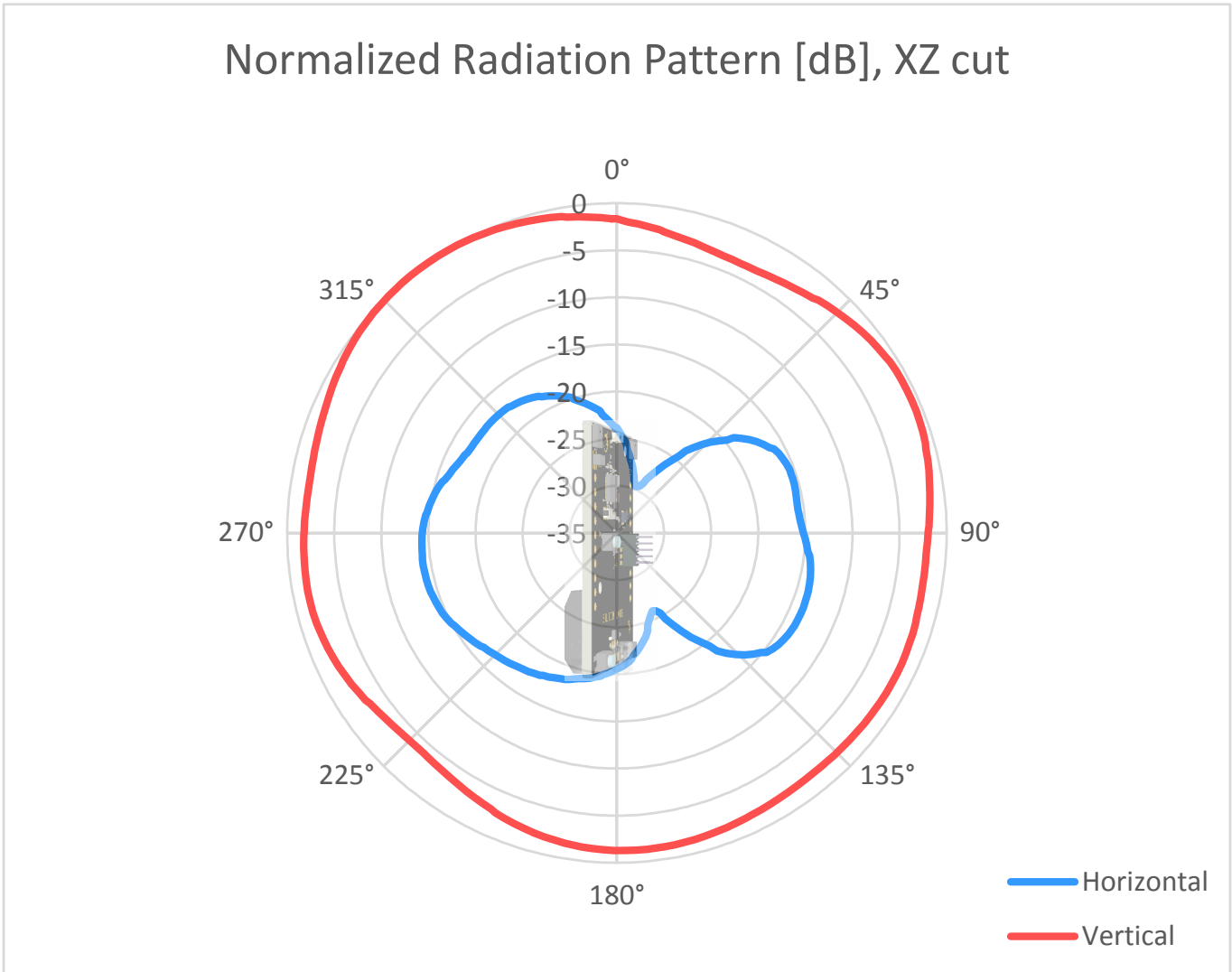


Figure 5.5. Antenna Pattern - XZ

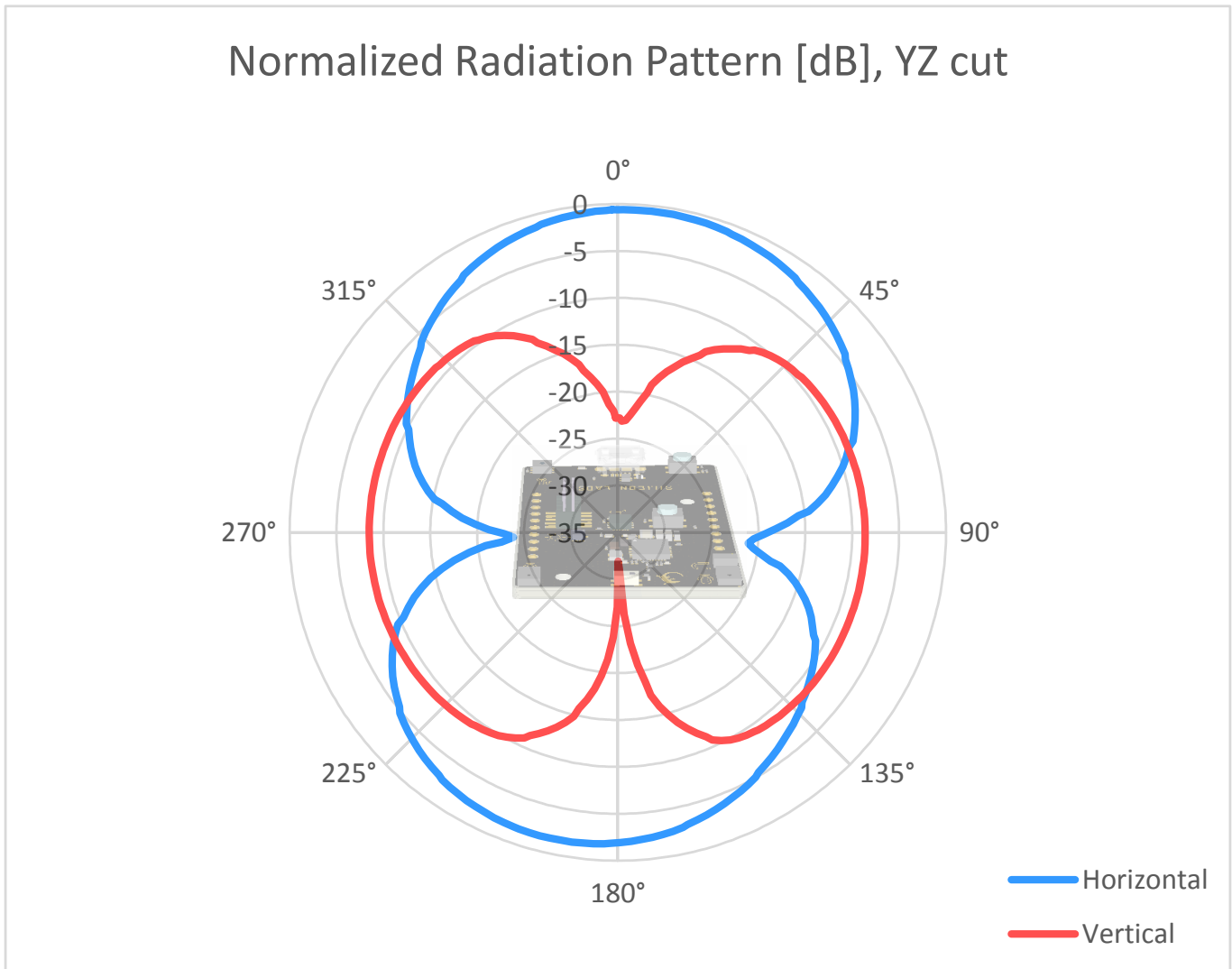


Figure 5.6. Antenna Pattern - YZ

5.5 EMC Compliance Recommendations

5.5.1 Recommendations for 2.4 GHz ETSI EN 300-328 Compliance

As shown in the previous chapter, with the EFR32BG27 output power set to 8 dBm, the radiated power of the BRD2602A fundamental complies with the 20 dBm limit of the ETSI EN 300-328. The harmonic emissions are under the applied limits with margin.

5.5.2 Recommendations for 2.4 GHz FCC 15.247 Compliance

As shown in the previous chapter, with the EFR32BG27 output power set to 8 dBm, the radiated power of the BRD2602A fundamental complies with the 30 dBm limit of the FCC 15.247. The harmonic emissions are under the applied limits with margin.

6. Schematics, Assembly Drawings, and BOM

Schematics, assembly drawings, and bill of materials (BOM) are available through Simplicity Studio when the kit documentation package has been installed. They are also available from the kit page on the Silicon Labs website: silabs.com.

7. Kit Revision History

The kit revision can be found printed on the box label of the kit, as outlined in the figure below. The kit revision history is summarized in the table below.

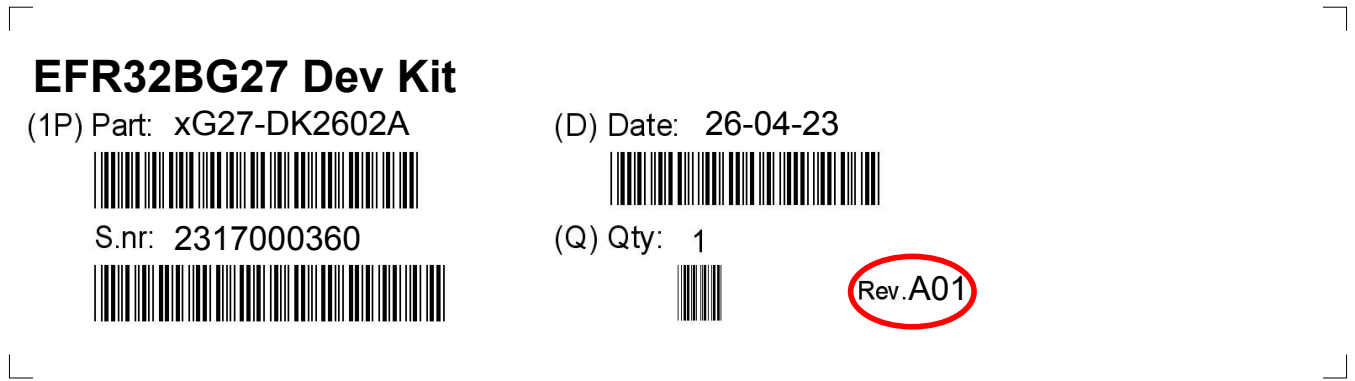


Figure 7.1. Revision Info

Table 7.1. Kit Revision History

Kit Revision	Released	Description
A01	26 April 2023	Updated board revision to BRD2602A Rev. A02, changed kit packaging.
A00	8 March 2023	Initial kit revision.

8. Board Revision History and Errata

8.1 Revision History

The board revision can be found laser printed on the board, and the board revision history is summarized in the following table.

Table 8.1. Board Revision History

Board	Released	Description
BRD2602A Rev. A02	19 April 2023	Updated antenna matching network.
BRD2602A Rev. A01	11 November 2022	Updated BG27 matching network.
BRD2602A Rev. A00	9 March 2022	Initial version.

8.2 Errata

There are no known errata at present.

9. Document Revision History

Revision 1.0

June 2023

- Initial document version.

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